Description
Perlast® G75H incorporates a novel reinforcement system which produces a synthetically clean compound formulated for minimum particle generation combined with excellent resistance to aggressive oxygen and fluorine based plasmas.

Specially developed for Plasma and Gas Deposition applications including ashing, etching, HDPCVD, PECVD, SACVD.

Particularly suited for use in applications which require exposure to temperatures of up to 320°C (608°F) combined with excellent mechanical properties.

Key Attributes
- Excellent plasma resistance
- High temperature stability
- Wide chemical resistance
- Low out-gassing properties making it ideal for vacuum applications
- Ultra low metal ion content
- Low coefficient of thermal expansion
- Outstanding physical properties make G75H ideal for dynamic applications.

Typical Applications
Developed for use in the semiconductor industry. Suitable for use in wet and dry semiconductor processes including:-
- Lithography
- PVD
- LPCVD, HDPCVD, PECVD, SACVD
- Etching
- Stripping
- Cleaning

Dynamic seals - Bonded Gate Valves & Isolation Valves
- Pendulum Valves
- Slit Valves

Static seals - Chamber O-rings
- Gas inlet seals
- Gas feed-through seals
- Chamber lid seals etc
- NW/KF fittings

Other components - Ceramics
- Quartz
- Sapphire

Other materials in this range
Perlast® G67P (translucent)
Perlast® G74P (translucent)
Perlast® G75TX (black high temperature grade 327°C/620°F)

*For extended operation at high temperature please consult the PPE technical team.